

構成可能レベルシフト、電圧変換、3 ステート出力搭載 SN74AVCH4T245 4 ビットデュアル電源バス トランシーバ

1 特長

- 制御入力 of V_{IH}/V_{IL} レベルは V_{CCA} 電圧を基準
- 完全に構成可能なデュアル レール設計により、1.2V ~ 3.6V の電源電圧の全範囲にわたって各ポートが動作可能
- 4.6V 許容の I/O
- I_{off} により部分的パワーダウン モードでの動作をサポート
- データ入力時のバス ホールドにより、外付けプルアップ / プルダウン抵抗が不要
- サポートされる最大データレート:
 - 380Mbps (1.8V から 3.3V への変換)
 - 200Mbps (<1.8V から 3.3V への変換)
 - 200Mbps (2.5V または 1.8V への変換)
 - 150Mbps (1.5V への変換)
 - 100Mbps (1.2V への変換)
- JESD 78, Class II 準拠で 100mA 超のラッチアップ性能
- JESD 22 を上回る ESD 保護:
 - 8000V、人体モデル (A114-A)
 - 200V、マシン モデル (A115-A)
 - 1000V、デバイス帯電モデル (C101)

2 アプリケーション

- パーソナル エレクトロニクス
- 産業用
- エンタープライズ
- テレコム

3 概要

この 4 ビット非反転バス トランシーバは、設定可能な 2 本の独立した電源レールを使用します。A ポートは V_{CCA} に追従するように設計されています。 V_{CCA} ピンには、1.2V ~ 3.6V の電源電圧を入力できます。B ポートは、 V_{CCB} に追従する設計になっています。 V_{CCB} ピンには、1.2V ~ 3.6V の電源電圧を入力できます。SN74AVCH4T245 は、 V_{CCA}/V_{CCB} を 1.2V ~ 3.6V に設定した場合の動作に最適化されています。最低 1.2V の V_{CCA}/V_{CCB} で動作します。これにより、1.2V、1.5V、1.8V、2.5V、3.3V の任意の電圧ノード間での自在な低電圧双方向変換が可能です。

SN74AVCH4T245 は、2 つのデータ バス間の非同期通信に設計されています。方向制御 (DIR) 入力および出

カイン ープル ($\overline{OE}$) 入力のロジック レベルに応じて、B ポート出力もしくは A ポート出力のいずれかがアクティブになるか、または、両方の出力ポートが高インピーダンスモードになります。本デバイスは、B ポート出力がアクティブになった場合、A バスから B バスヘデータを転送し、A ポート出力がアクティブになった場合、B バスから A バスヘデータを転送します。A ポートと B ポートの入力回路はどちらも常にアクティブであるため、これらのポートには論理 High または Low レベルを印加して、 I_{CC} と I_{CCZ} が過剰に流れないようにする必要があります。

SN74AVCH4T245 デバイスの制御ピン (1DIR、2DIR、1OE、2OE) は、 V_{CCA} から電源供給されます。

このデバイスは、 I_{off} を使用する部分的パワーダウン アプリケーション用の動作が完全に規定されています。 I_{off} 回路で出力をディセーブルすることにより、電源切断時にデバイスに電流が逆流して損傷するのを回避できます。

V_{CC} 絶縁機能は、いずれかの V_{CC} 入力 that GND レベルになると、両方のポートが高インピーダンス状態になるよう設計されています。電源オン側のバス ホールド回路は常にアクティブのままです。

アクティブなバス ホールド回路により、使用されていないデータ入力や駆動されていないデータ入力は、有効なロジック状態に保持されます。バス ホールド回路と、プルアップまたはプルダウン抵抗との併用は推奨しません。電源オン側のバス ホールド回路は常にアクティブのままです。

電源投入または電源オフの間にデバイスを高インピーダンス状態にするには、 $\overline{OE}$ ピンをプルアップ抵抗を介して V_{CC} に接続します。この抵抗の最小値は、ドライバの電流シンク能力によって決まります。

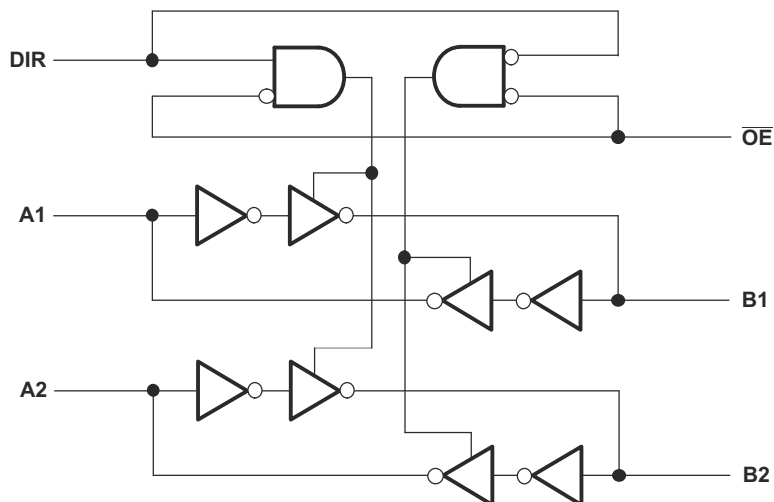
パッケージ情報

部品番号	パッケージ ⁽¹⁾	パッケージ サイズ ⁽²⁾
SN74AVCH4T245	D (SOIC, 16)	9.9mm × 6mm
	PW (TSSOP, 16)	5mm × 6.4mm
	DGV (TVSOP, 16)	3.6mm × 6.4mm
	RSV (UQFN, 16)	2.6mm × 1.8mm
	RGY (VQFN, 16)	4mm × 3.5mm

(1) 詳細については、[セクション 11](#) を参照してください。

(2) パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。





SN74AVCH4T245 の 1/2 の論理図 (正論理)

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4 Pin Configuration and Functions

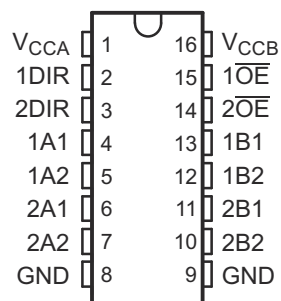


図 4-1. D, DGV, or PW Packages
16-Pin SOIC, TVSOP, or TSSOP
Top View

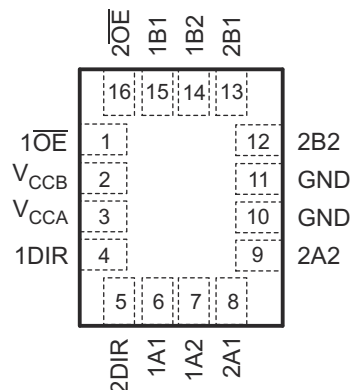


図 4-2. RSV Package
16-Pin UQFN
Top View

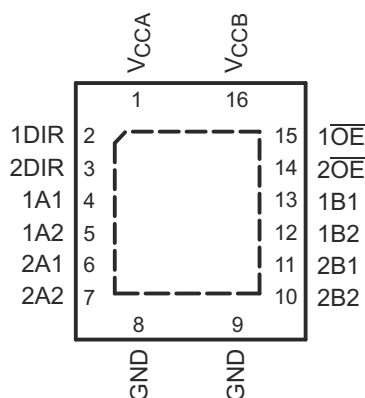


図 4-3. RGY Package
16-Pin VQFN
Top View

表 4-1. Pin Functions

PIN			TYPE	DESCRIPTION
NAME	SOIC, TVSOP, TSSOP, VQFN	UQFN		
1A1	4	6	I/O	Input/output 1A1. Referenced to V_{CCA} .
1A2	5	7	I/O	Input/output 1A2. Referenced to V_{CCA} .
1B1	13	15	I/O	Input/output 1B1. Referenced to V_{CCA} .
1B2	12	14	I/O	Input/output 1B2. Referenced to V_{CCA} .
1DIR	2	4	I	Direction-control input for 1 ports.
1OE	15	1	I	3-state output-mode enables. Pull OE high to place '1' outputs in 3-state mode. Referenced to V_{CCA} .
2A1	6	8	I/O	Input/output 2A1. Referenced to V_{CCA} .
2A2	7	9	I/O	Input/output 2A2. Referenced to V_{CCA} .
2B1	11	13	I/O	Input/output 2B1. Referenced to V_{CCA} .
2B2	10	12	I/O	Input/output 2B2. Referenced to V_{CCA} .
2DIR	3	5	I	Direction-control input for 2 ports.
2OE	14	16	I	3-state output-mode enables. Pull OE high to place '2' outputs in 3-state mode. Referenced to V_{CCA} .
GND	8, 9	10, 11	-	Ground.
V_{CCA}	1	3	-	A-port power supply voltage. $1.2V \leq V_{CCA} \leq 3.6V$.
V_{CCB}	16	2	-	B-port power supply voltage. $1.2V \leq V_{CCA} \leq 3.6V$.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

			MIN	MAX	UNIT
V_{CCA}	Supply voltage A		–0.5	4.6	V
V_{CCB}	Supply voltage B		–0.5	4.6	V
V_I	Input Voltage ⁽²⁾	I/O Ports (A Port)	–0.5	4.6	V
		I/O Ports (B Port)	–0.5	4.6	
		Control Inputs	–0.5	4.6	
V_O	Voltage applied to any output in the high-impedance or power-off state ⁽²⁾	A Port	–0.5	4.6	V
		B Port	–0.5	4.6	
V_O	Voltage applied to any output in the high or low state ^{(2) (3)}	A Port	–0.5	$V_{CCA} + 0.5$	V
		B Port	–0.5	$V_{CCB} + 0.5$	
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CCA} , V_{CCB} , or GND			±100	mA
T_J	Junction Temperature			150	°C
T_{stg}	Storage temperature		–65	150	°C

- (1) Stresses beyond those listed under [セクション 5.1](#) may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under [セクション 5.3](#). Exposure beyond the limits listed in [セクション 5.3](#) may affect device reliability.
- (2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The output positive-voltage rating may be exceeded up to 6.5V maximum if the output current rating is observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±8000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	
		Machine model, per A115-A	200	

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾ ⁽²⁾ ⁽³⁾ ⁽⁴⁾ ⁽⁵⁾

			V _{CCI}	V _{CCO}	MIN	MAX	UNIT
V _{CCA}	Supply voltage A				1.2	3.6	V
V _{CCB}	Supply voltage B				1.2	3.6	
V _{IH}	High-level input voltage	Data inputs ⁽⁴⁾	1.2V to 1.95V		V _{CCI} × 0.65		V
			1.95V to 2.7V		1.6		V
			2.7V to 3.6V		2		V
V _{IL}	Low-level input voltage	Data inputs ⁽⁴⁾	1.2V to 1.95V		V _{CCI} × 0.35		V
			1.95V to 2.7V		0.7		V
			2.7V to 3.6V		0.8		V
V _{IH}	High-level input voltage	DIR (referenced to V _{CCA}) ⁽⁵⁾	1.2V to 1.95V		V _{CCA} × 0.65		V
			1.95V to 2.7V		1.6		
			2.7V to 3.6V		2		
V _{IL}	Low-level input voltage	DIR (referenced to V _{CCA}) ⁽⁵⁾	1.2V to 1.95V		V _{CCA} × 0.35		V
			1.95V to 2.7V		0.7		
			2.7V to 3.6V		0.8		
V _I	Input voltage				0	3.6	V
V _O	Output voltage	Active state			0	V _{CCO}	V
		3-state			0	3.6	
I _{OH}	High-level output current			1.2V		–3	mA
				1.4V to 1.6V		–6	
				1.65V to 1.95V		–8	
				2.3V to 2.7V		–9	
				3V to 3.6V		–12	
I _{OL}	Low-level output current			1.2V		3	mA
				1.4V to 1.6V		6	
				1.65V to 1.95V		8	
				2.3V to 2.7V		9	
				3V to 3.6V		12	
Δt/Δv	Input transition rise and fall time					5	ns/V
T _A	Operating free-air temperature				–40	85	°C

- (1) V_{CCI} is the V_{CC} associated with the input port.
- (2) V_{CCO} is the V_{CC} associated with the output port.
- (3) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, [Implications of Slow or Floating CMOS Inputs](#).
- (4) For V_{CCI} values not specified in the data sheet, V_{IH} min = V_{CCI} × 0.7V, V_{IL} max = V_{CCI} × 0.3V
- (5) For V_{CCA} values not specified in the data sheet, V_{IH} min = V_{CCA} × 0.7V, V_{IL} max = V_{CCI} × 0.3V

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74AVCH4T245					UNIT
		D (SOIC)	DGV (TVSOP)	PW (TSSOP)	RGY (VQFN)	RSV (UQFN)	
		6 PINS	6 PINS	6 PINS	6 PINS	6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	85.5	126	102.8	68.8	146.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	46.9	50.8	35.9	70.6	53.6	
$R_{\theta JB}$	Junction-to-board thermal resistance	43	57.7	57.5	45	75.6	
Ψ_{JT}	Junction-to-top characterization parameter	13.4	5.7	1.6	11.9	13.5	
Ψ_{JB}	Junction-to-board characterization parameter	42.7	57.2	56.9	44.7	75.6	
$R_{\theta JC(bottom)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	28.2	N/A	

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

PARAMETER		TEST CONDITIONS		V _{CCA}	V _{CCB}	Operating free-air temperature (TA)			UNIT
						–40°C to 85°C			
						MIN	TYP	MAX	
V _{OH}		I _{OH} = –100μA	V _I = V _{IH}	1.2V to 3.6V	1.2V to 3.6V	V _{CCO} – 0.2			V
		I _{OH} = –3mA		1.2V	1.2V	0.95			
		I _{OH} = –6mA		1.4V	1.4V	1.05			
		I _{OH} = –8mA		1.65V	1.65V	1.2			
		I _{OH} = –9mA		2.3V	2.3V	1.75			
		I _{OH} = –12mA		3V	3V	2.3			
V _{OL}		I _{OL} = 100μA	V _I = V _{IL}	1.2V to 3.6V	1.2V to 3.6V	0.2			V
		I _{OL} = 3mA		1.2V	1.2V	0.15			
		I _{OL} = 6mA		1.4V	1.4V	0.35			
		I _{OL} = 8mA		1.65V	1.65V	0.45			
		I _{OL} = 9mA		2.3V	2.3V	0.55			
		I _{OL} = 12mA		3V	3V	0.7			
I _I	DIR	V _I = V _{CCA} or GND		1.2V to 3.6V	1.2V to 3.6V	–1	0.025	1	μA
I _{BHL}	Bus-hold low sustainin g current Port A or Port B ⁽⁶⁾	V _I = 0.42V		1.2V	1.2V	25			μA
		V _I = 0.49V		1.4V	1.4V	15			
		V _I = 0.58V		1.65V	1.65V	25			
		V _I = 0.7V		2.3V	2.3V	45			
		V _I = 0.8V		3V	3V	100			
I _{BHH}	Bus-hold high sustainin g current Port A or Port B ⁽⁷⁾	V _I = 0.78V		1.2V	1.2V	–25			μA
		V _I = 0.91V		1.4V	1.4V	–15			
		V _I = 1.07V		1.65V	1.65V	–25			
		V _I = 1.6V		2.3V	2.3V	–45			
		V _I = 2V		3V	3V	–100			

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

PARAMETER		TEST CONDITIONS		V _{CCA}	V _{CCB}	Operating free-air temperature (TA)			UNIT
						–40°C to 85°C			
						MIN	TYP	MAX	
I _{BHLO}	Bus-hold low overdrive current ⁽⁸⁾	Ramp input up V _I = 0 to V _{CCI}		1.2	1.2	50			μA
				1.6	1.6	125			
				1.95V	1.95V	200			
				2.7V	2.7V	300			
				3.6V	3.6V	500			
I _{BHHO}	Bus-hold high overdrive current ⁽⁹⁾	Ramp input down V _I = V _{CCI} to 0		1.2	1.2	-50			μA
				1.6	1.6	–125			
				1.95V	1.95V	–200			
				2.7V	2.7V	–300			
				3.6V	3.6V	–500			
I _{off}	A port	V _I or V _O = 0V - 3.6V		0V	0V to 3.6V	–5	0.1	5	μA
	B port			0V to 3.6V	0V	–5	0.1	5	
I _{OZ}	B port	V _I = or V _O = 0 to 3.6V		0V	3.6V	–5	0.5	5	μA
	A port			3.6V	0V	–5	0.5	5	
I _{CCA}		V _I = V _{CCI} or GND	I _O = 0	1.2V to 3.6V	1.2V to 3.6V	8			μA
				0V	3.6V	–2			
				3.6V	0V	8			
I _{CCB}		V _I = V _{CCB} or GND	I _O = 0	1.2V to 3.6V	1.2V to 3.6V	8			μA
				0V	3.6V	8			
				3.6V	0V	–2			
I _{CCA} + I _{CCB}		V _I = V _{CCI} or GND	I _O = 0	1.2V to 3.6V	1.2V to 3.6V	16			μA
C _i	Control Input	V _I = 3.3V or GND		3.3V	3.3V	3.5 4.5			pF
C _{io}	A or B port	V _O = 3.3V or GND		3.3V	3.3V	6 7			pF

 (1) V_{CCI} is the V_{CC} associated with the input port.

 (2) V_{CCO} is the V_{CC} associated with the output port.

5.6 Switching Characteristics, $V_{CCA} = 1.2V$

over recommended operating free-air temperature range, $V_{CCA} = 1.2V$ (see Figure 6-1)

PARAMETER	FROM	TO	B-Port Supply Voltage (V_{CCB})					UNIT
			1.2V	1.5V	1.8V	2.5V	3.3V	
			TYP	TYP	TYP	TYP	TYP	
t_{PLH}	A	B	3.4	2.9	2.7	2.6	2.8	ns
t_{PHL}			3.4	2.9	2.7	2.6	2.8	
t_{PLH}	B	A	3.6	3.1	2.8	2.6	2.6	
t_{PHL}			3.6	3.1	2.8	2.6	2.6	
t_{PHZ}	$\overline{OE}$	A	5.6	4.7	4.3	3.9	3.7	ns
t_{PLZ}			5.6	4.7	4.3	3.9	3.7	
t_{PHZ}	$\overline{OE}$	B	5	4.3	3.9	3.6	3.6	
t_{PLZ}			5	4.3	3.9	3.6	3.6	
t_{PZH}	$\overline{OE}$	A	6.2	5.2	5.2	4.3	4.8	ns
t_{PZL}			6.2	5.2	5.2	4.3	4.8	
t_{PZH}	$\overline{OE}$	B	5.9	5.1	5	4.7	5.5	
t_{PZL}			5.9	5.1	5	4.7	5.5	

5.7 Switching Characteristics, $V_{CCA} = 1.5 \pm 0.1V$

over recommended operating free-air temperature range, $V_{CCA} = 1.5 \pm 0.1V$ (see Figure 6-1)

PARAMETER	FROM	TO	B-Port Supply Voltage (V _{CCB})												UNIT														
			1.2V			1.5 ± 0.1V			1.8 ± 0.15V			2.5 ± 0.2V				3.3 ± 0.3V													
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		MIN	TYP	MAX											
t _{PLH}	A	B	3.2			0.3			6.3			0.3			5.2			0.4			4.2			0.4			4.2		
t _{PHL}			3.2			0.3			6.3			0.3			5.2			0.4			4.2			0.4			4.2		
t _{PLH}	B	A	3.3			0.7			6.3			0.5			6			0.4			5.7			0.3			5.6		
t _{PHL}			3.3			0.7			6.3			0.5			6			0.4			5.7			0.3			5.6		
t _{PHZ}	OE	A	4.9			1.4			9.6			1.1			9.5			0.7			9.4			0.4			9.4		
t _{PLZ}			4.9			1.4			9.6			1.1			9.5			0.7			9.4			0.4			9.4		
t _{PHZ}	OE	B	4.5			1.4			9.6			1.1			7.7			0.9			5.8			0.9			5.6		
t _{PLZ}			4.5			1.4			9.6			1.1			7.7			0.9			5.8			0.9			5.6		
t _{PZH}	OE	A	5.6			1.8			10.2			1.5			10.2			1.3			10.2			1.6			10.2		
t _{PZL}			5.6			1.8			10.2			1.5			10.2			1.3			10.2			1.6			10.2		
t _{PZH}	OE	B	5.2			1.9			10.3			1.9			9.1			1.4			7.4			1.2			7.6		
t _{PZL}			5.2			1.9			10.3			1.9			9.1			1.4			7.4			1.2			7.6		

5.8 Switching Characteristics, $V_{CCA} = 1.8 \pm 0.15V$

over recommended operating free-air temperature range, $V_{CCA} = 1.8V \pm 0.15V$ (see Figure 6-1)

PARAMETER	FROM	TO	B-Port Supply Voltage (V _{CCB})														UNIT									
			1.2V			1.5 ± 0.1V			1.8 ± 0.15V			2.5 ± 0.2V			3.3 ± 0.3V											
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP		MAX								
t _{PLH}	A	B	2.9			0.1			6	0.1			4.9			0.1			3.9			ns				
t _{PHL}			2.9			0.1			6	0.1			4.9			0.1			3.9							
t _{PLH}	B	A	3			0.6			5.3	0.5			4.9			0.3			4.6				4.5			
t _{PHL}			3			0.6			5.3	0.5			4.9			0.3			4.6				4.5			
t _{PHZ}	OE	A	4.4			1			7.4	1			7.3			0.6			7.3			0.4			7.2	ns
t _{PLZ}			4.4			1			7.4	1			7.3			0.6			7.3			0.4			7.2	
t _{PHZ}	OE	B	4.1			1.2			9.2	1			7.4			0.8			5.3			0.8			4.6	
t _{PLZ}			4.1			1.2			9.2	1			7.4			0.8			5.3			0.8			4.6	
t _{PZH}	OE	A	5.4			1.6			8.6	1.8			8.7			1.3			8.7			1.6			8.7	ns
t _{PZL}			5.4			1.6			8.6	1.8			8.7			1.3			8.7			1.6			8.7	
t _{PZH}	OE	B	5			1.7			9.9	1.6			8.7			1.2			6.9			1			6.9	
t _{PZL}			5			1.7			9.9	1.6			8.7			1.2			6.9			1			6.9	

5.9 Switching Characteristics, $V_{CCA} = 2.5 \pm 0.2V$

over recommended operating free-air temperature range, $V_{CCA} = 2.5 \pm 0.2V$ (see Figure 6-1)

PARAMETER	FROM	TO	B-Port Supply Voltage (V _{CCB})												UNIT															
			1.2V			1.5 ± 0.1V			1.8 ± 0.15V			2.5 ± 0.2V				3.3 ± 0.3V														
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		MIN	TYP	MAX												
t _{PLH}	A	B	2.8			0.1			5.7			0.1			4.6			0.2			3.5			0.1			3.6			ns
t _{PHL}			2.8			0.1			5.7			0.1			4.6			0.2			3.5			0.1			3.6			
t _{PLH}	B	A	2.7			0.6			4.2			0.4			3.9			0.2			3.4			0.2			3.3			
t _{PHL}			2.7			0.6			4.2			0.4			3.9			0.2			3.4			0.2			3.3			
t _{PHZ}	OE	A	4			0.7			6.5			0.7			5.2			0.6			4.8			0.4			4.8			ns
t _{PLZ}			4			0.7			6.5			0.7			5.2			0.6			4.8			0.4			4.8			
t _{PHZ}	OE	B	3.8			0.9			8.8			0.8			7			0.6			4.8			0.6			4			
t _{PLZ}			3.8			0.9			8.8			0.8			7			0.6			4.8			0.6			4			
t _{PZH}	OE	A	4.7			1			8.4			1			8.4			1			6.2			1			6.6			ns
t _{PZL}			4.7			1			8.4			1			8.4			1			6.2			1			6.6			
t _{PZH}	OE	B	4.5			1.5			9.4			1.3			8.2			1.1			6.2			0.9			5.2			
t _{PZL}			4.5			1.5			9.4			1.3			8.2			1.1			6.2			0.9			5.2			

5.10 Switching Characteristics, $V_{CCA} = 3.3 \pm 0.3V$

over recommended operating free-air temperature range, $V_{CCA} = 3.3 \pm 0.3V$ (see Figure 6-1)

PARAMETER	FROM	TO	B-Port Supply Voltage (V _{CCB})												UNIT															
			1.2V			1.5 ± 0.1V			1.8 ± 0.15V			2.5 ± 0.2V				3.3 ± 0.3V														
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		MIN	TYP	MAX												
t _{PLH}	A	B	2.9			0.1			5.6			0.1			4.5			0.1			3.3			0.1			2.9			ns
t _{PHL}			2.9			0.1			5.6			0.1			4.5			0.1			3.3			0.1			2.9			
t _{PLH}	B	A	2.6			0.6			4.2			0.4			3.4			0.2			3			0.1			2.8			
t _{PHL}			2.6			0.6			4.2			0.4			3.4			0.2			3			0.1			2.8			
t _{PHZ}	OE	A	3.8			0.6			8.7			0.6			5.2			0.6			3.8			0.4			3.8			ns
t _{PLZ}			3.8			0.6			8.7			0.6			5.2			0.6			3.8			0.4			3.8			
t _{PHZ}	OE	B	3.7			0.8			8.7			0.6			6.8			0.5			4.7			0.5			3.8			
t _{PLZ}			3.7			0.8			8.7			0.6			6.8			0.5			4.7			0.5			3.8			
t _{PZH}	OE	A	4.8			0.7			9.3			0.7			8.3			0.7			5.6			0.7			6.6			ns
t _{PZL}			4.8			0.7			9.3			0.7			8.3			0.7			5.6			0.7			6.6			
t _{PZH}	OE	B	5.3			1.4			9.3			1.2			8.1			1			6.4			0.8			6.2			
t _{PZL}			5.3			1.4			9.3			1.2			8.1			1			6.4			0.8			6.2			

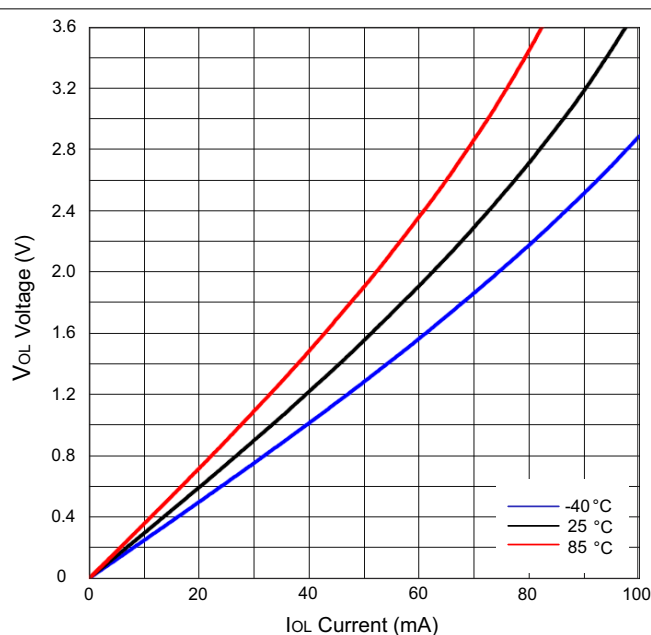
5.11 Operating Characteristics

$T_A = 25^\circ C$

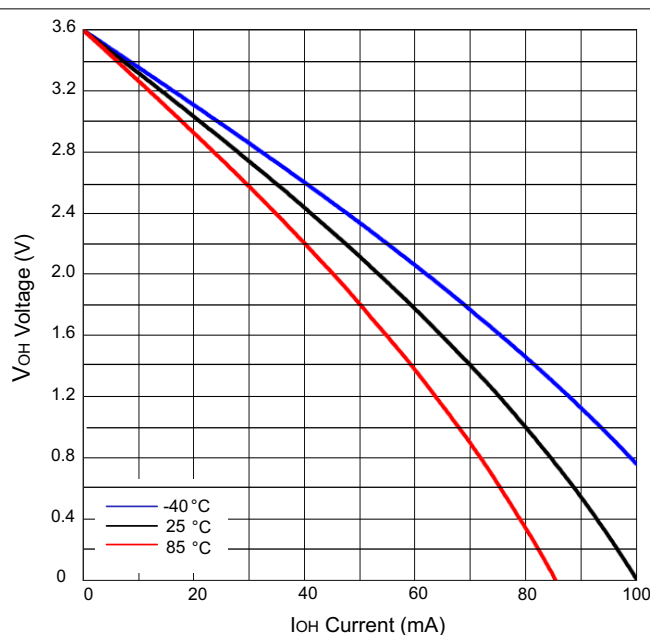
PARAMETER			TEST CONDITIONS	B-Port Supply Voltage (V_{CCB})					UNIT
				1.2V	1.5V	1.8V	2.5V	3.3V	
				TYP	TYP	TYP	TYP	TYP	
C_{pdA} ⁽¹⁾	A-port input, B-port output	Outputs enabled	$C_L = 0pF$, $f = 10MHz$, $t_r = t_f = 1ns$	1	1	1	1.5	2	pF
		Outputs disabled		1	1	1	1	1	
	B-port input, A-port output	Outputs enabled		12	12.5	13	14	15	
		Outputs disabled		1	1	1	1	1	
C_{pdB} ⁽¹⁾	A-port input, B-port output	Outputs enabled	$C_L = 0pF$, $f = 10MHz$, $t_r = t_f = 1ns$	12	12.5	13	14	15	pF
		Outputs disabled		1	1	1	1	1	
	B-port input, A-port output	Outputs enabled		1	1	1	1	2	
		Outputs disabled		1	1	1	1	1	

(1) Power dissipation capacitance per transceiver

5.12 Typical Characteristics

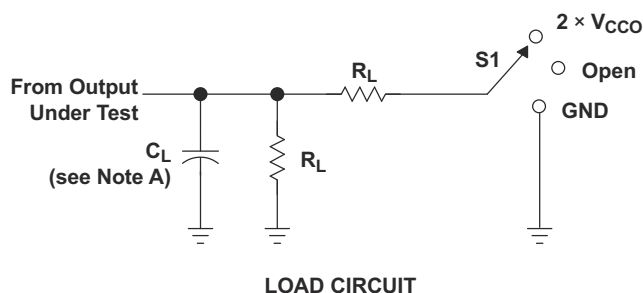


5-1. Low-Level Output Voltage (V_{OL})
 vs Low-Level Current (I_{OL})

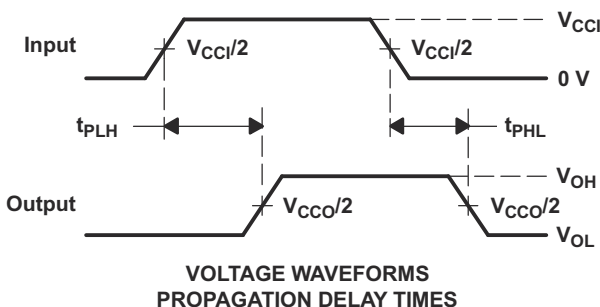


5-2. High-Level Output Voltage (V_{OH})
 vs High-Level Current (I_{OH})

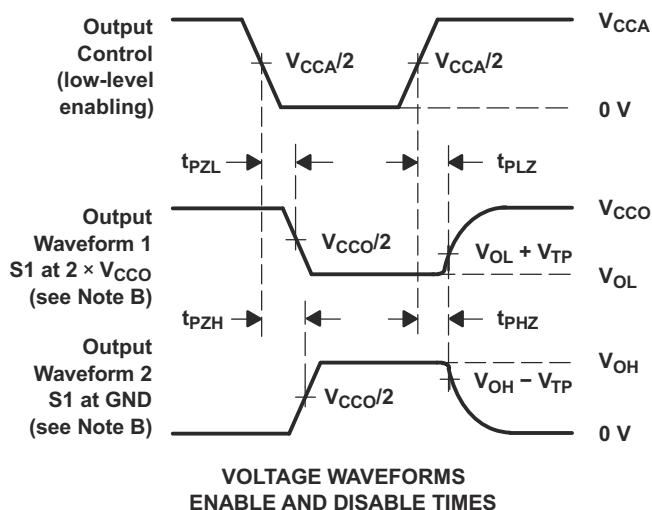
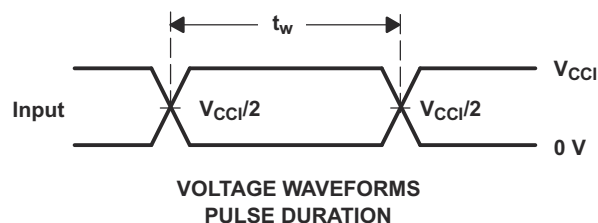
6 Parameter Measurement Information



V_{CCO}	C_L	R_L	V_{TP}
1.2 V	15 pF	2 k Ω	0.1 V
1.5 V $\pm$ 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V $\pm$ 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V $\pm$ 0.2 V	15 pF	2 k Ω	0.15 V
3.3 V $\pm$ 0.3 V	15 pF	2 k Ω	0.3 V



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CCO}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR = 10 MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1$ V/ns, $dv/dt \geq 1$ V/ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - V_{CCI} is the V_{CC} associated with the input port.
 - V_{CCO} is the V_{CC} associated with the output port.

6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SN74AVCH4T245 is a 4-bit, dual-supply noninverting bidirectional voltage level translation device. Ax pins and control pins (1DIR, 2DIR, 1 $\overline{OE}$, and 2 $\overline{OE}$) are supported by V_{CCA} , and Bx pins are supported by V_{CCB} . The A port can accept I/O voltages ranging from 1.2V to 3.6V, while the B port can accept I/O voltages from 1.2V to 3.6V. A high on DIR allows data transmission from Ax to Bx and a low on DIR allows data transmission from Bx to Ax when $\overline{OE}$ is set to low. When $\overline{OE}$ is set to high, both Ax and Bx pins are in the high-impedance state. For more information, refer to the [AVC Logic Family Technology and Applications](#) application report.

7.2 Functional Block Diagram

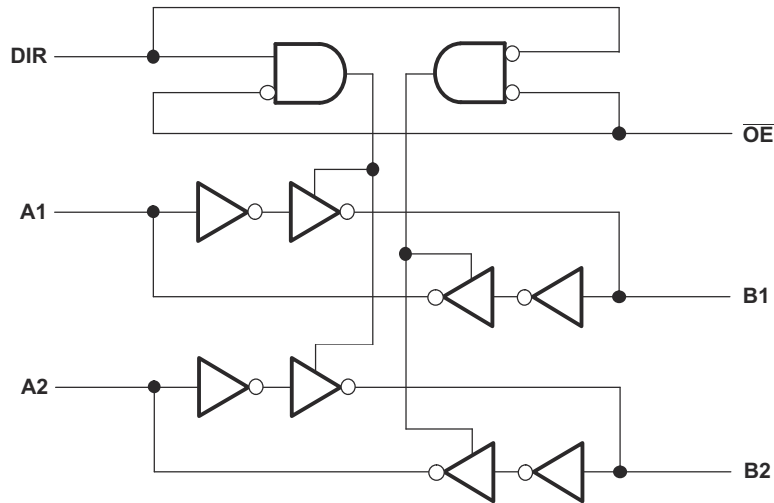


図 7-1. Logic Diagram (Positive Logic) for 1/2 of SN74AVCH4T245

7.3 Feature Description

7.3.1 Fully Configurable Dual-Rail Design

Fully configurable dual-rail design allows each port to operate over the full 1.2V to 3.6V power-supply range.

Both V_{CCA} and V_{CCB} can be supplied at any voltage between 1.2V and 3.6V; thus, making the device an excellent choice for translating between any of the low voltage nodes (1.2V, 1.8V, 2.5V, and 3.3V).

7.3.2 Supports High Speed Translation

The SN74AVCH4T245 device can support high data rate applications. The translated signal data rate can be up to 380Mbps when the signal is translated from 1.8V to 3.3V.

7.3.3 I_{off} Supports Partial-Power-Down Mode Operation

I_{off} will prevent backflow current by disabling I/O output circuits when device is in partial-power-down mode.

7.3.4 Bus-Hold Circuitry

This device has active bus-hold circuitry that holds unused or undriven inputs at a valid logic state. Use of pull-up or pull-down resistors with the bus-hold circuitry is not recommended (Refer to the [Bus-Hold Circuit](#) application report). Pullup and pulldown resistors are not recommended on the inputs of devices with bus-hold. Unused inputs can be left floating.

7.3.5 Vcc Isolation Feature

The VCC isolation feature is designed so that if either V_{CCA} or V_{CCB} are at GND (or < 0.4V), both ports will be in a high-impedance state (I_{OZ} shown in [セクション 5.5](#)). This prevents false logic levels from being presented to either bus.

7.4 Device Functional Modes

表 7-1 lists the functional modes of the SN74AVCH4T245.

表 7-1. Function Table (Each 2-Bit Section)

CONTROL INPUTS ⁽¹⁾		OUTPUT CIRCUITS		OPERATION
$\overline{OE}$	DIR	A PORT	B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	H	Hi-Z	Enabled	A data to B bus
H	X	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os are always active.

8 Application and Implementation

Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The SN74AVCH4T245 device can be used in level-shifting applications for interfacing devices or systems operating at different interface voltages with one another. The SN74AVCH4T245 device is an excellent choice for applications where a push-pull driver is connected to the data I/Os. The maximum data rate can be up to 380Mbps when device translates a signal from 1.8V to 3.3V.

8.2 Typical Application

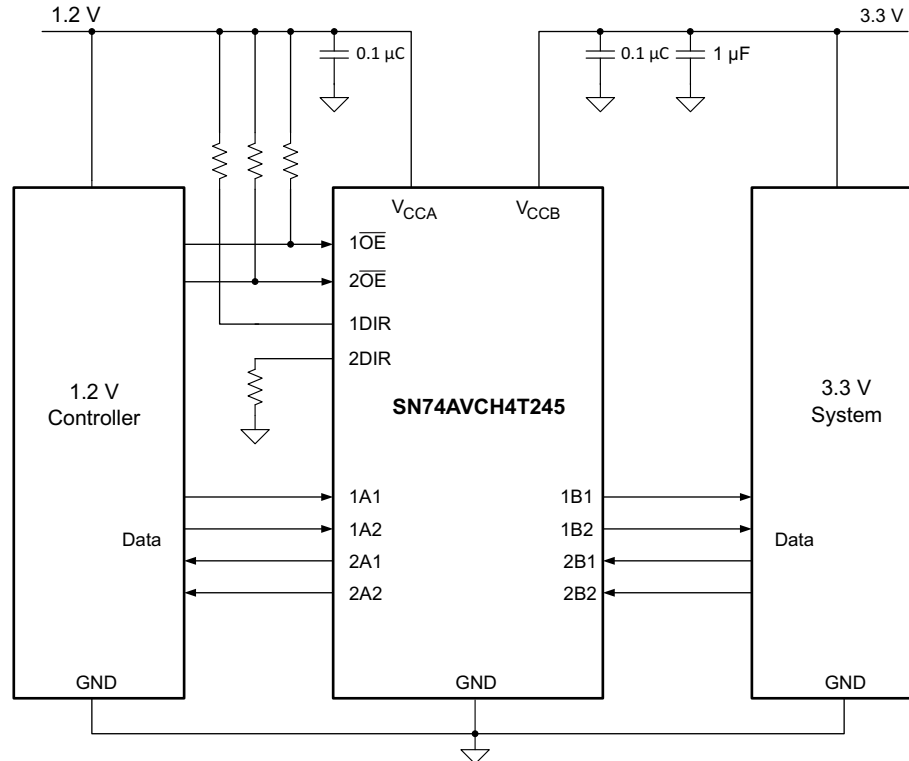


図 8-1. Typical Application Diagram

8.2.1 Design Requirements

For the design example shown in [セクション 8.2](#) use the parameters listed in [表 8-1](#).

表 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.2V to 3.6V
Output voltage range	1.2V to 3.6V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
 - Use the supply voltage of the device that is driving the SN74AVCH4T245 device to determine the input voltage range. For a valid logic high, the value must exceed the V_{IH} of the input port. For a valid logic low, the value must be less than the V_{IL} of the input port.
- Output voltage range
 - Use the supply voltage of the device that the SN74AVCH4T245 device is driving to determine the output voltage range.

8.2.3 Application Curve

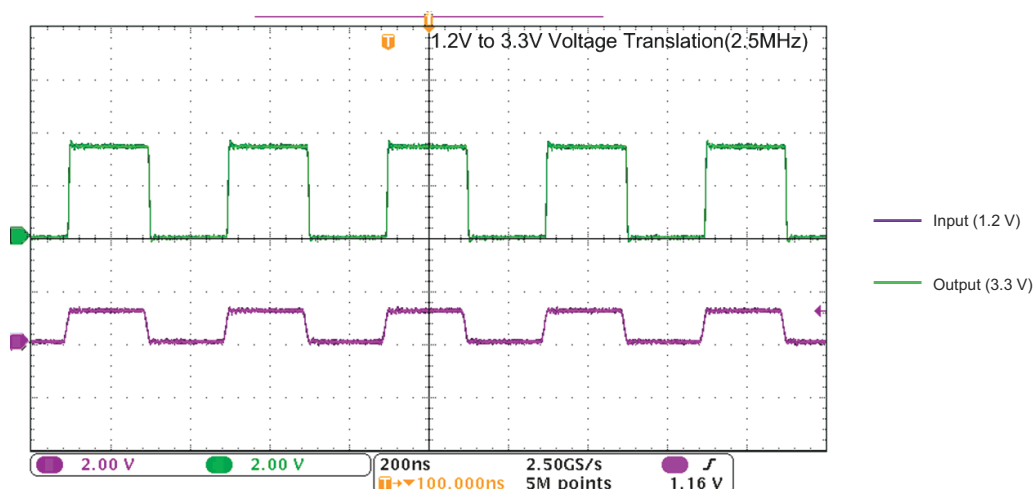


図 8-2. Translation Up (1.2V to 3.3V) at 2.5MHz

8.3 Power Supply Recommendations

The SN74AVCH4T245 device uses two separate configurable power-supply rails, V_{CCA} and V_{CCB} . V_{CCA} accepts any supply voltage from 1.2V to 3.6V, and V_{CCB} accepts any supply voltage from 1.2V to 3.6V. The A port and B port are designed to track V_{CCA} and V_{CCB} respectively allowing for low voltage bidirectional translation between any of the 1.2V, 1.5V, 1.8V, 2.5V, and 3.3V voltage nodes.

The output-enable ($\overline{OE}$) input circuit is designed so that it is supplied by V_{CCA} , and all outputs are placed in the high-impedance state when the $\overline{OE}$ input is high. To put the outputs in the high-impedance state during power up or power down, the $\overline{OE}$ input pin must be tied to V_{CCA} through a pull-up resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The current-sinking capability of the driver determines the minimum value of the pull-up resistor to V_{CCA} .

V_{CCA} or V_{CCB} can be powered up first. If the SN74AVCH4T245 is powered up in a permanently enabled state, pull-up resistors are recommended at the input. This allows for proper or glitch-free power-up. For more

information, refer to [Designing with SN74LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters](#) application note.

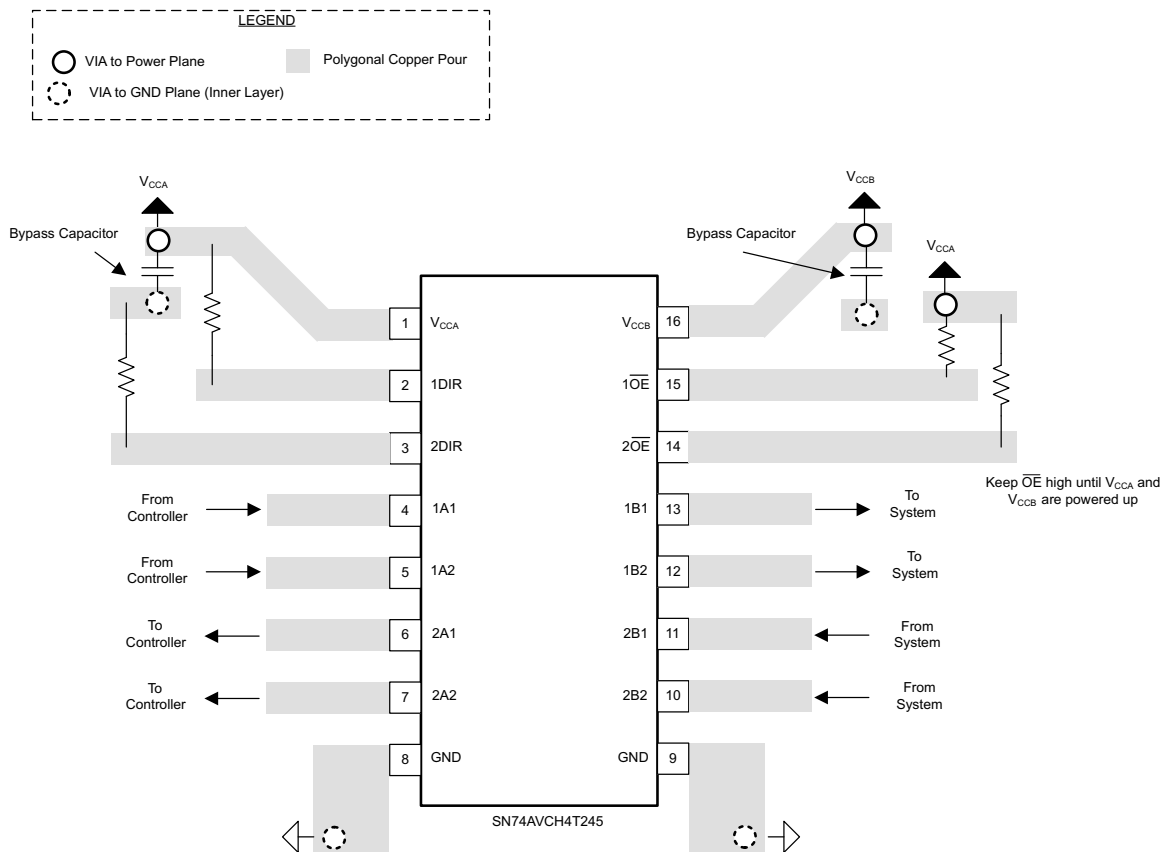
8.4 Layout

8.4.1 Layout Guidelines

For device reliability, it is recommended to follow common printed-circuit board layout guidelines such as:

- Use bypass capacitors on power supplies.
- Use short trace lengths to avoid excessive loading.
- Place pads on the signal paths for loading capacitors or pull-up resistors to help adjust rise and fall times of signals, depending on the system requirements.

8.4.2 Layout Example



8-3. Layout Recommendation

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Designing with SN74LVCXT245 and SN74LVCHXT245 Family of Direction Controlled Voltage Translators/Level-Shifters](#)
- Texas Instruments, [Bus-Hold Circuit](#)
- Texas Instruments, [AVC Logic Family Technology and Applications](#)

9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.3 サポート・リソース

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9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision E (November 2015) to Revision F (February 2025)	Page
• Updated PW and RGY Thermal Information	8

Changes from Revision D (June 2007) to Revision E (November 2015)	Page
• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。	1
• Changed Pin Functions table	4

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74AVCH4T245PWRG4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
74AVCH4T245PWTE4	Active	Production	TSSOP (PW) 16	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
74AVCH4T245PWTG4	Active	Production	TSSOP (PW) 16	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
74AVCH4T245RGYRG4	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WS245
74AVCH4T245RGYRG4.A	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WS245
74AVCH4T245RGYRG4.B	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WS245
74AVCH4T245RSVR-NT	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
74AVCH4T245RSVR-NT.A	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
74AVCH4T245RSVR-NT.B	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
74AVCH4T245RSVRG4	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
74AVCH4T245RSVRG4.A	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
74AVCH4T245RSVRG4.B	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
SN74AVCH4T245D	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH4T245
SN74AVCH4T245D.B	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH4T245
SN74AVCH4T245DGVR	Active	Production	TVSOP (DGV) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245DGVR.B	Active	Production	TVSOP (DGV) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH4T245
SN74AVCH4T245DR.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH4T245
SN74AVCH4T245DT	Active	Production	SOIC (D) 16	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH4T245
SN74AVCH4T245DT.B	Active	Production	SOIC (D) 16	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH4T245
SN74AVCH4T245PW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PW.B	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PWE4	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PWR.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PWT	Active	Production	TSSOP (PW) 16	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245PWT.B	Active	Production	TSSOP (PW) 16	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WS245
SN74AVCH4T245RGYR	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WS245

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AVCH4T245RGYR.A	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WS245
SN74AVCH4T245RGYR.B	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	WS245
SN74AVCH4T245RSVR	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
SN74AVCH4T245RSVR.A	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV
SN74AVCH4T245RSVR.B	Active	Production	UQFN (RSV) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ZWV

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74AVCH4T245 :

- Automotive : [SN74AVCH4T245-Q1](#)
- Enhanced Product : [SN74AVCH4T245-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AVCH4T245RGYRG4	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1
74AVCH4T245RSVR-NT	UQFN	RSV	16	3000	180.0	8.4	2.0	2.8	0.7	4.0	8.0	Q1
74AVCH4T245RSVRG4	UQFN	RSV	16	3000	180.0	12.4	2.1	2.9	0.75	4.0	12.0	Q1
SN74AVCH4T245DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AVCH4T245DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AVCH4T245PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AVCH4T245PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AVCH4T245RGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

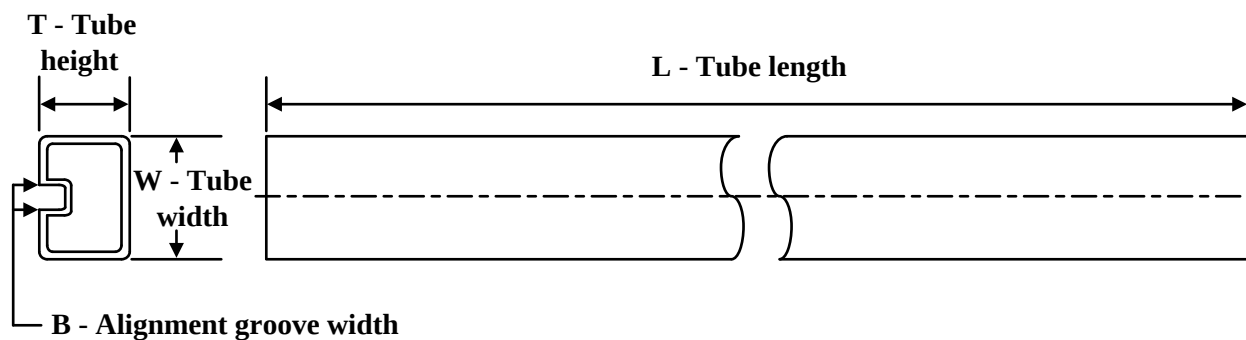
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AVCH4T245RGYRG4	VQFN	RGY	16	3000	353.0	353.0	32.0
74AVCH4T245RSVR-NT	UQFN	RSV	16	3000	200.0	183.0	25.0
74AVCH4T245RSVRG4	UQFN	RSV	16	3000	200.0	183.0	25.0
SN74AVCH4T245DGVR	TVSOP	DGV	16	2000	353.0	353.0	32.0
SN74AVCH4T245DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74AVCH4T245PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74AVCH4T245PWT	TSSOP	PW	16	250	353.0	353.0	32.0
SN74AVCH4T245RGYR	VQFN	RGY	16	3000	353.0	353.0	32.0

TUBE

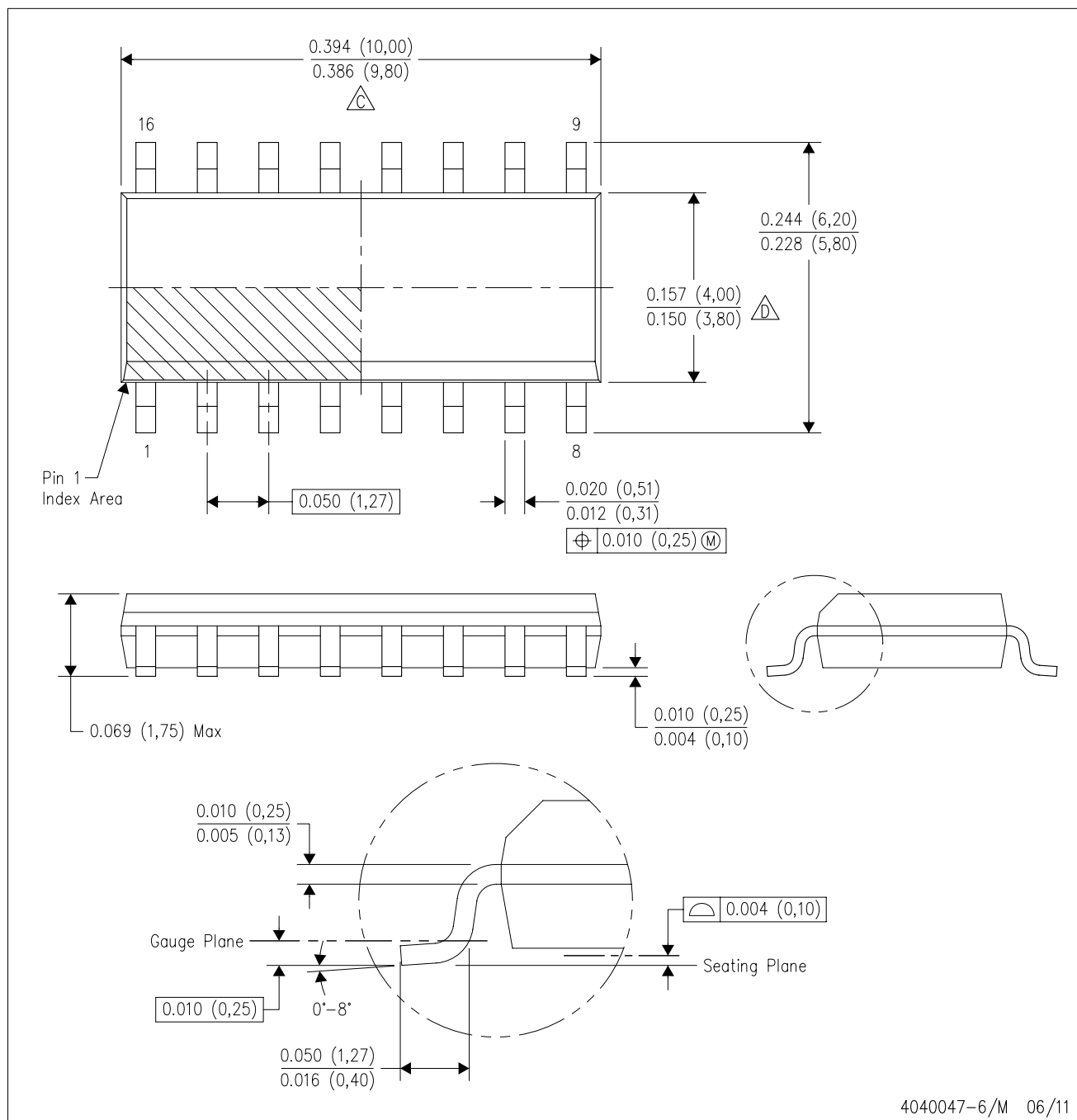


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74AVCH4T245D	D	SOIC	16	40	507	8	3940	4.32
SN74AVCH4T245D.B	D	SOIC	16	40	507	8	3940	4.32
SN74AVCH4T245PW	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74AVCH4T245PW.B	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74AVCH4T245PWE4	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

GENERIC PACKAGE VIEW

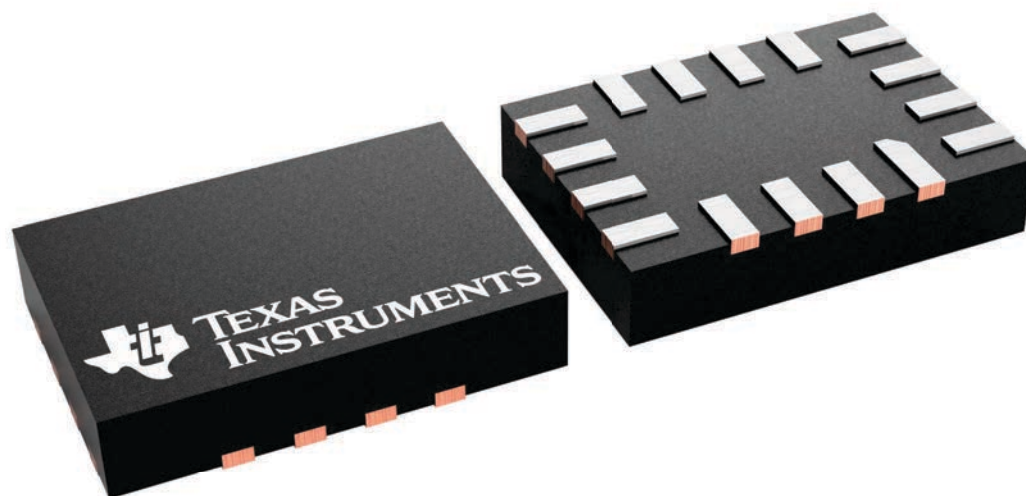
RSV 16

UQFN - 0.55 mm max height

1.8 x 2.6, 0.4 mm pitch

ULTRA THIN QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.





1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

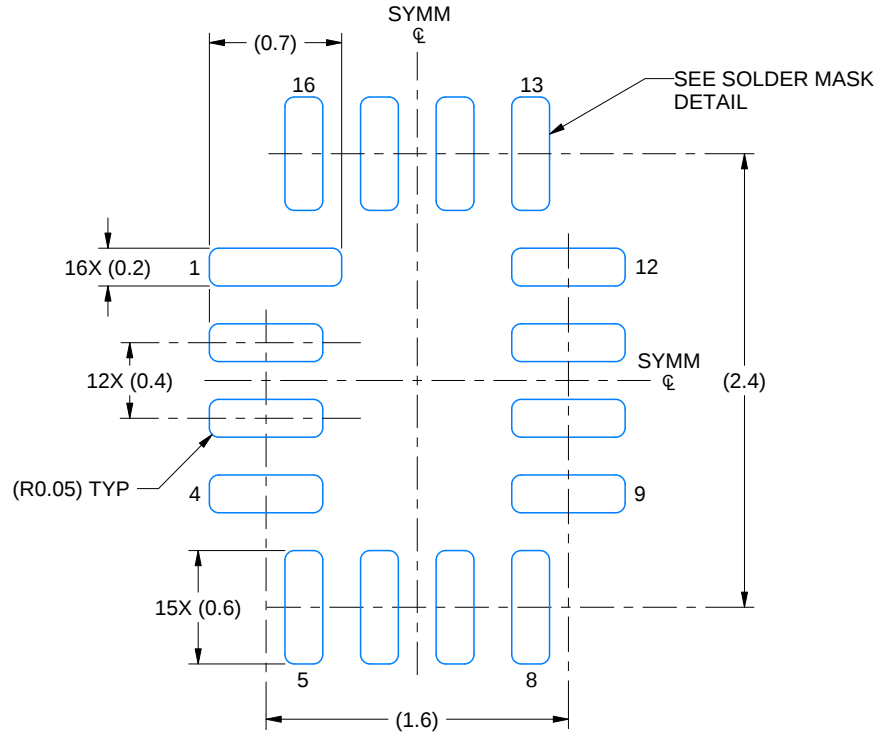
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

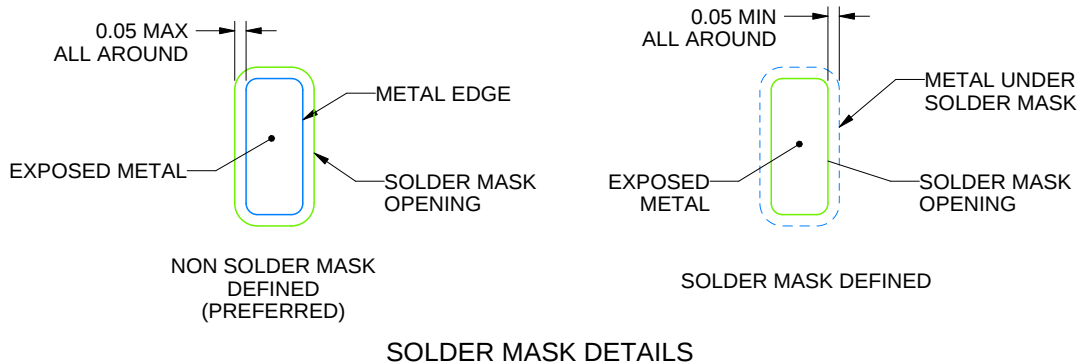
RSV0016A

UQFN - 0.55 mm max height

ULTRA THIN QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X



4220314/C 02/2020

NOTES: (continued)

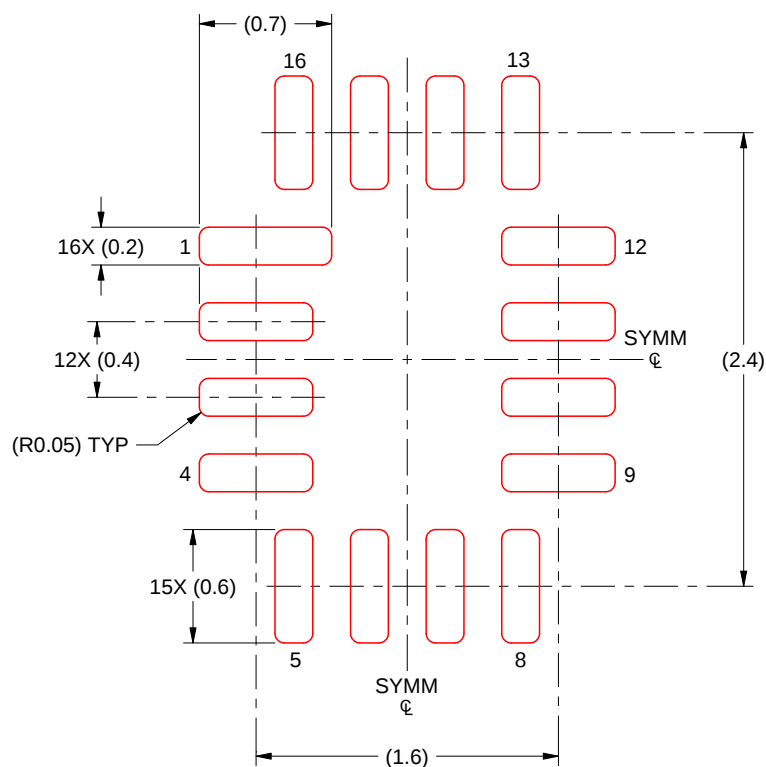
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).

EXAMPLE STENCIL DESIGN

RSV0016A

UQFN - 0.55 mm max height

ULTRA THIN QUAD FLATPACK - NO LEAD

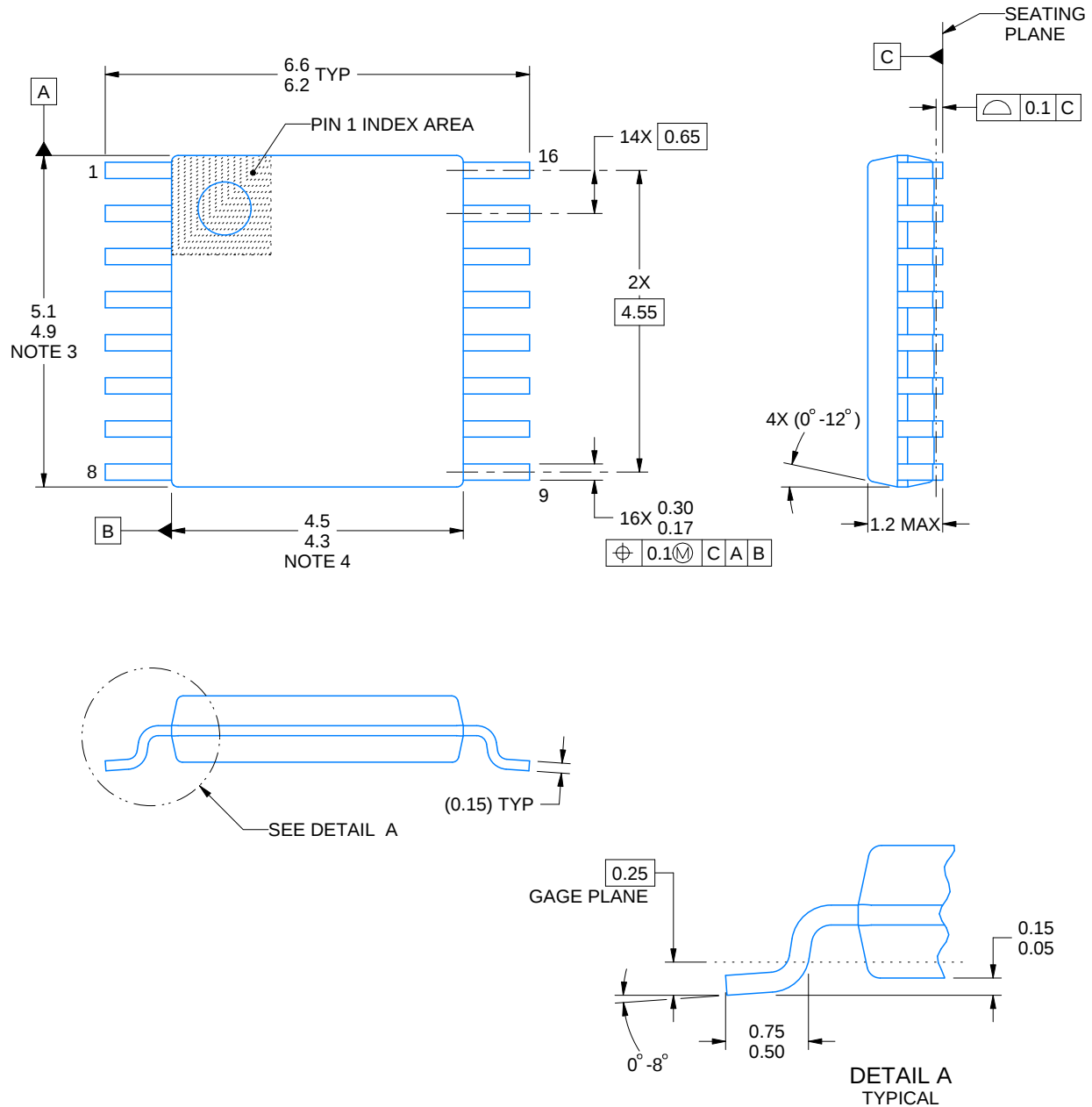
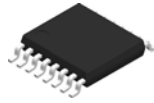


SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 25X

4220314/C 02/2020

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



4220204/B 12/2023

NOTES:

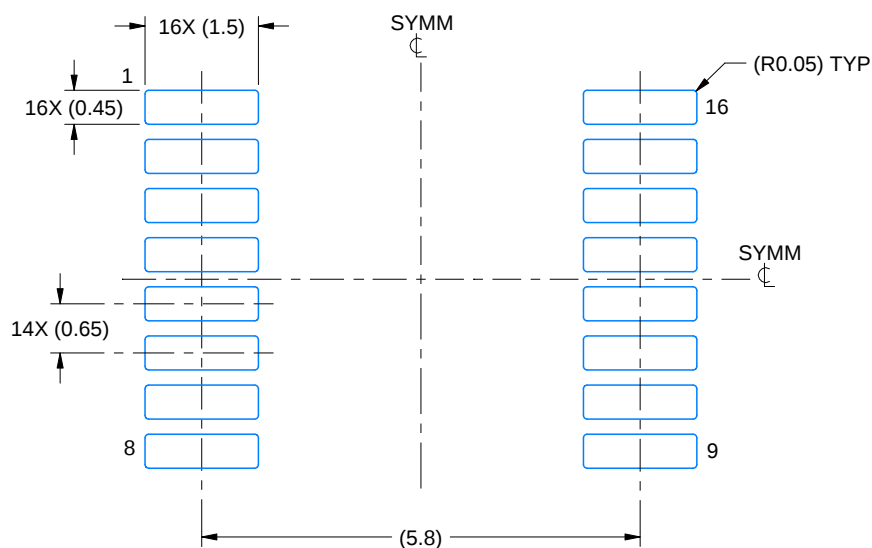
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

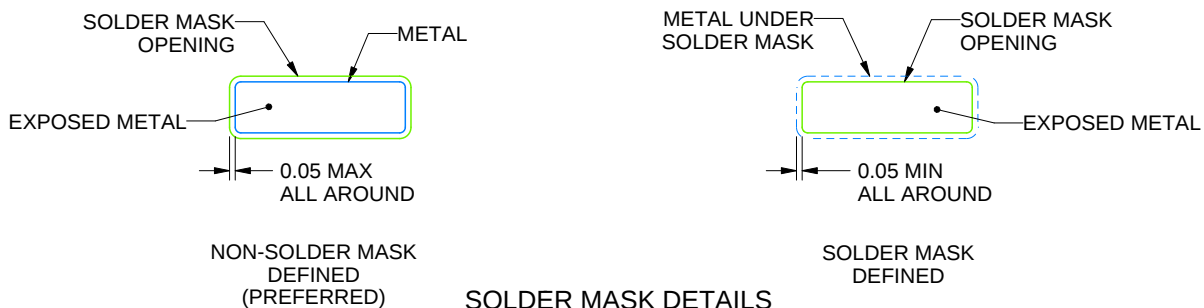
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

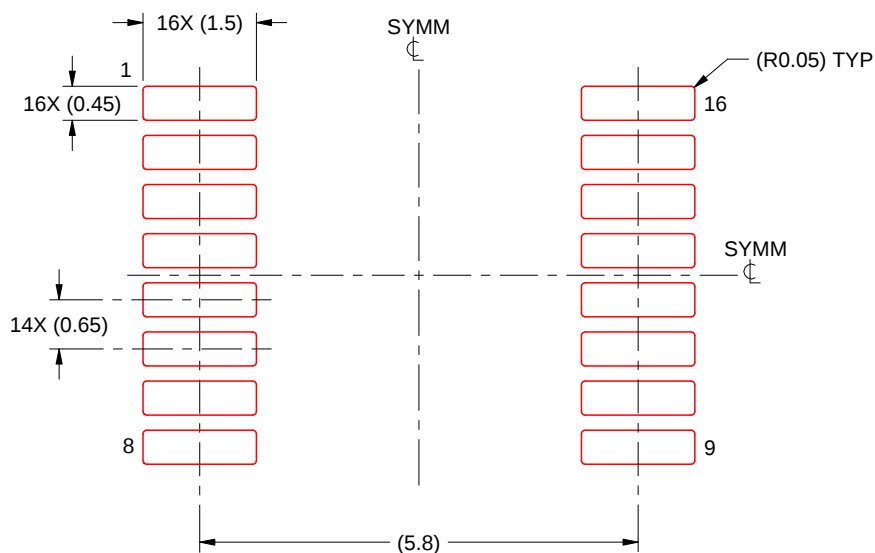
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

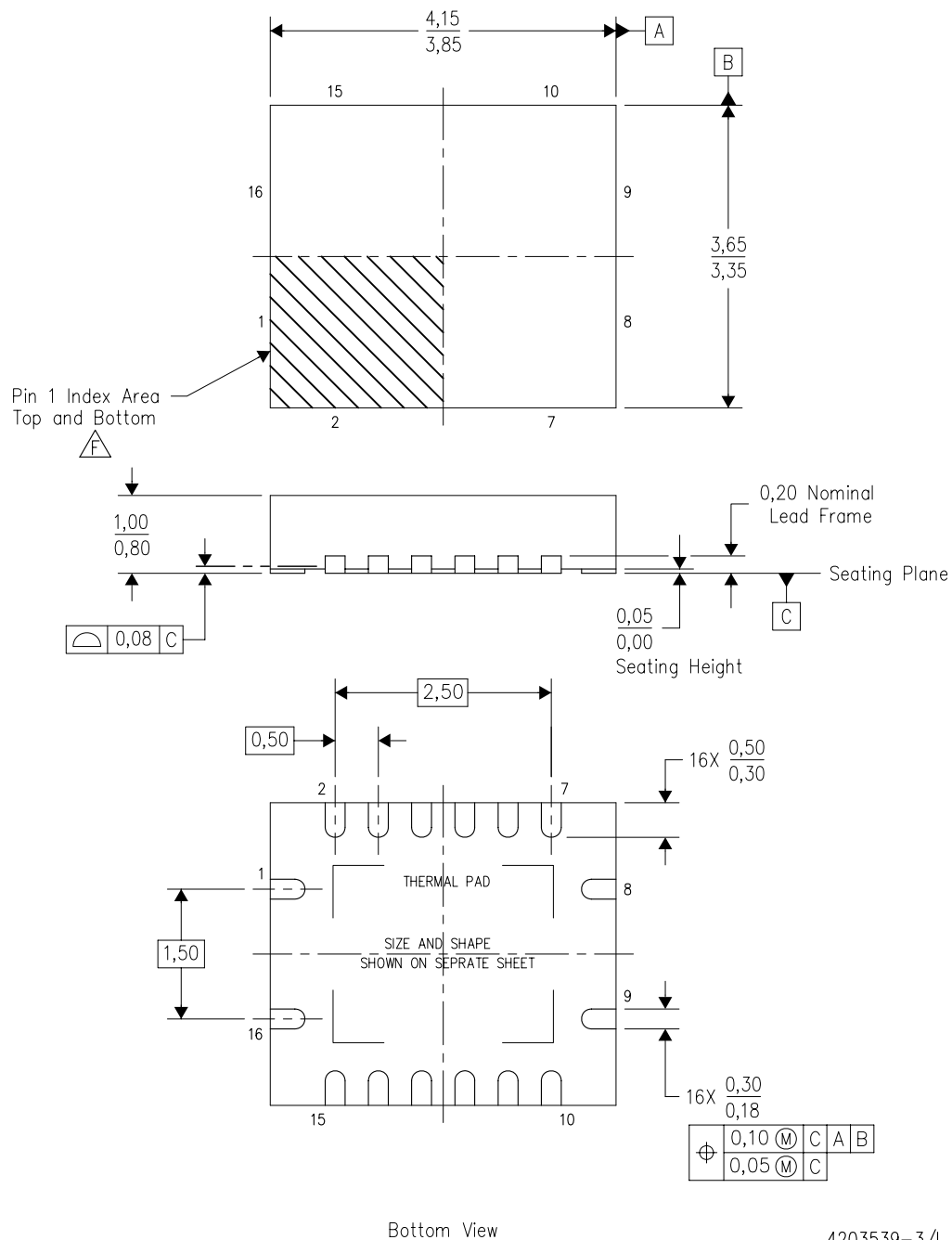
4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-3/I 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N16)

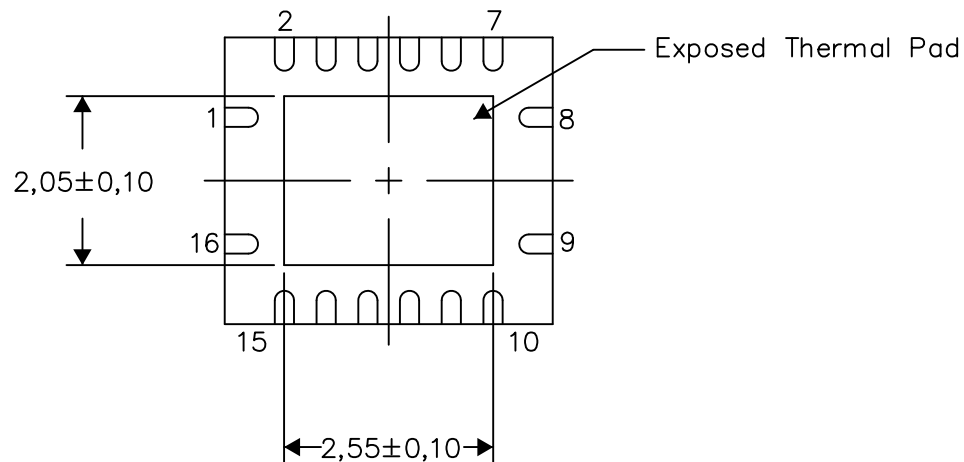
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

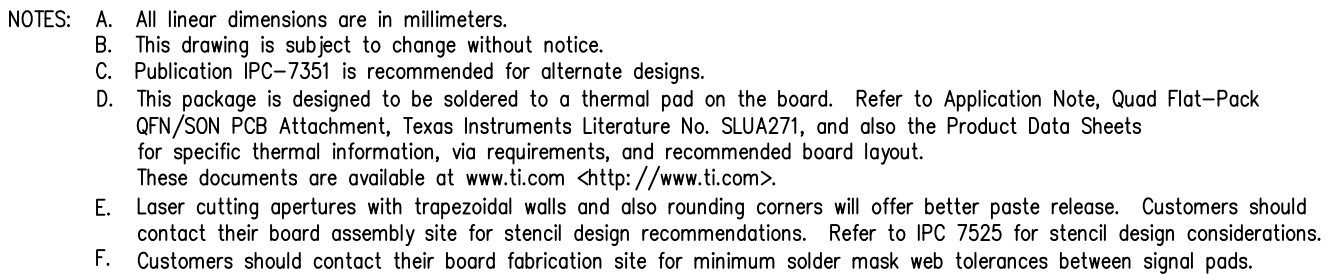


Bottom View

Exposed Thermal Pad Dimensions

4206353-3/P 03/14

NOTE: All linear dimensions are in millimeters



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